IEEE COINS 2023
IEEE International Conference on Omni-layer Intelligent Systems

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Berlin, Germany | Hybrid
July 23-25, 2023
https://coinsconf.com

Call for Papers

Track: Big Data

The aim of this track is to provide a forum for the exchange of ideas and discussions on Big Data problems, algorithms, modern architectures as well as current and future challenges in this topic. The track is therefore open to high quality submissions from researchers working in learning problems using Big Data Analytics. The topics of this track include Big Data fundamentals, modern architectures to work on the cloud as well as any Big Data application.

A) Big Data fundamentals

- Data Visualization and Modern Technologies
- Big Data Analytics and Mining
- Software Frameworks (MapReduce, etc)
- Big Data Preprocessing Techniques
- Scalable and High Performant Analytics
- Modeling, Experiments

B) Modern Architectures - Services Computing and Databases

- Cloud Computing
- SQL/NoSQL Databases
- Mobile Computing
- Streaming, Sensors, Wireless Technologies
- Big Data Platforms (Management, Analytics)

C) Applications of Big Data

- Networking and Social Networks
- Social Science and Implications for Big Data
- Security, Privacy and Risk
- Bioinformatics
- Internet of Things
- Smart Cities & Energy
- Industrial Challenges

Track Program Committee

Zhifeng Bao, RMIT University, Australia
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Submission Instructions

- Submission information for the conference can be found here.
- Use IEEE templates in Microsoft Word (US Letter) and LaTeX format for conference proceedings.
- Final PDF file should be created using IEEE PDF eXpress.